3.3 V/5 V ECL Coaxial Cable Driver

MC10EP89

Description

The MC10EP89 is a differential fanout gate specifically designed to drive coaxial cables. The device is especially useful in digital video broadcasting applications; for this application, since the system is polarity free, each output can be used as an independent driver. The driver produces swings 70% larger than a standard ECL output. When driving a coaxial cable, proper termination is required at both ends of the line to minimize signal loss. The 1.6 V (5 V) and 1.4 V (3.3 V) swing allow for termination at both ends of the cable, while maintaining a 800 mV (5 V) and 700 mV (3.3 V) swing at the receiving end of the cable. Because of the larger output swings, the device cannot be terminated into the standard V_{CC}-2.0 V. All of the DC parameters are tested with a 50 Ω to V_{CC}-3.0 V load. The driver accepts a standard differential ECL input and can run off of the digital video broadcast standard -5.0 V supply.

Features

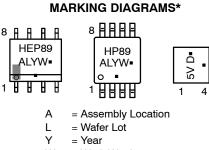
- 310 ps Typical Propagation Delay
- Maximum Frequency > 2 GHz Typical
- 1.6 V (5 V) and 1.4 V (3.3 V) V_{OUTpp} Swing
- PECL Mode Operating Range: V_{CC} = 3.0 V to 5.5 V with V_{EE} = 0 V
- NECL Mode Operating Range: $V_{CC} = 0 V$ with $V_{EE} = -3.0 V$ to -5.5 V
- Open Input Default State
- Safety Clamp on Inputs
- Q Output Will Default LOW with Inputs Open or at V_{EE}
- These Devices are Pb–Free, Halogen Free and are RoHS Compliant



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- W = Work Week
- D = Date Code
- = Pb-Free Package

(Note: Microdot may be in either location)

*For additional marking information, refer to Application Note <u>AND8002/D</u>.

ORDERING INFORMATION

Device	Package	Shipping [†]
MC10EP89DG	SOIC-8 (Pb-Free)	98 Units / Tube
MC10EP89DTG	TSSOP-8 (Pb-Free)	100 Units / Tube
MC10EP89DTR2G	TSSOP-8 (Pb-Free)	2500 / Tape & Reel
MC10EP89MNR4G	DFN8 (Pb-Free)	1000 / Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

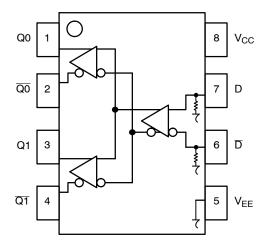


Table 1. PIN DESCRIPTION

PIN	FUNCTION
D*, <u>D</u> *	ECL Data Inputs
Q0, Q1, <u>Q0</u> , <u>Q1</u>	ECL Data Outputs
V _{CC}	Positive Supply
V _{EE}	Negative Supply

* Pins will default LOW when left open.

Figure 1. 8-Lead Pinout (Top View) and Logic Diagram

Table 2. ATTRIBUTES

Characteristics	Value
ernal Input Pulldown Resistor ernal Input Pullup Resistor D Protection Human Body Model Aachine Model Charged Device Model isture Sensitivity, Indefinite Time Out of Drypack (Note 1) SOIC-8 SSOP-8 DFN8 mmability Rating Dxygen Index: 28 to 34	75 kΩ
Internal Input Pullup Resistor	N/A
ESD Protection Human Body Model Machine Model Charged Device Model	> 4 kV > 200 V > 2 kV
Moisture Sensitivity, Indefinite Time Out of Drypack (Note 1)	Pb-Free Pkg
SOIC-8 TSSOP-8 DFN8	Level 1 Level 3 Level 1
Flammability Rating Oxygen Index: 28 to 34	UL-94 V-0 @ 0.125 in
Transistor Count	152 Devices
Meets or exceeds JEDEC Spec EIA/JESD78 IC Latchup Test	

1. For additional information, see Application Note AND8003/D.

Table 3. MAXIMUM RATINGS

Symbol	Parameter	Condition 1	Condition 2	Rating	Unit
V _{CC}	PECL Mode Power Supply	V _{EE} = 0 V		6	V
V_{EE}	NECL Mode Power Supply	V _{CC} = 0 V		-6	V
VI	PECL Mode Input Voltage NECL Mode Input Voltage	V _{EE} = 0 V V _{CC} = 0 V	$V_I \leq V_{CC} \\ V_I \geq V_{EE}$	6 -6	V V
l _{out}	Output Current	Continuous Surge		50 100	mA mA
TA	Operating Temperature Range			-40 to +85	°C
T _{stg}	Storage Temperature Range			–65 to +150	°C
θ_{JA}	Thermal Resistance (Junction-to-Ambient)	0 lfpm 500 lfpm	8 SOIC 8 SOIC	190 130	°C/W °C/W
θ_{JC}	Thermal Resistance (Junction-to-Case)	Standard Board	8 SOIC	41 to 44	°C/W
θ_{JA}	Thermal Resistance (Junction-to-Ambient)	0 lfpm 500 lfpm	8 TSSOP 8 TSSOP	185 140	°C/W °C/W
θ_{JC}	Thermal Resistance (Junction-to-Case)	Standard Board	8 TSSOP	41 to 44	°C/W
θ_{JA}	Thermal Resistance (Junction-to-Ambient)	0 lfpm 500 lfpm	DFN8 DFN8	129 84	°C/W °C/W
T _{sol}	Wave Solder (Pb-Free)	<2 to 3 sec @ 260°C		265	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

			-40°C			25°C		85°C				
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit	
I _{EE}	Power Supply Current	24	30	36	26	34	40	30	36	42	mA	
V _{OH}	Output HIGH Voltage (Note 3)	2130	2255	2405	2180	2336	2455	2200	2400	2475	mV	
V _{OL}	Output LOW Voltage (Note 3)	500	784	1100	480	786	1100	440	882	1060	mV	
V _{IH}	Input HIGH Voltage (Single-Ended)	2070		2410	2170		2490	2240		2580	mV	
VIL	Input LOW Voltage (Single-Ended)	1350		1800	1350		1820	1350		1855	mV	
VIHCMR	Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 4)	2.0		3.3	2.0		3.3	2.0		3.3	V	
I _{IH}	Input HIGH Current			150			150			150	μA	
۱ _{IL}	Input LOW Current	0.5			0.5			0.5			μA	

Table 4. DC CHARACTERISTICS, PECL V_{CC} = 3.3 V, V_{EE} = 0 V (Note 2)

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm.

2. Input and output parameters vary 1:1 with V_{CC} . V_{EE} can vary +0.3 V to -0.3 V. 3. All loading with 50 Ω to V_{CC} - 3.0 V. 4. V_{IHCMR} min varies 1:1 with V_{EE} , max varies 1:1 with V_{CC} . The V_{IHCMR} range is referenced to the most positive side of the differential input signal.

Table 5. DC CHARACTERISTICS, P	PECL V _{CC} = 5.0 V, V _{EE} = 0 V (Note 5)
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		-40°C			25°C			85°C			
Symbol	Characteristic	Min	Min Typ Max		Min	Тур	Max	Min	Тур	Max	Unit
I _{EE}	Power Supply Current	27	34	41	30	37	44	33	40	47	mA
V _{OH}	Output HIGH Voltage (Note 6)	3830	3955	4105	3880	4037	4155	3900	4102	4175	mV
V _{OL}	Output LOW Voltage (Note 6)	1900	2205	2500	1850	2265	2450	1850	2177	2450	mV
V _{IH}	Input HIGH Voltage (Single-Ended)	3770		4110	3870		4190	3940		4280	mV
V _{IL}	Input LOW Voltage (Single-Ended)	3050		3500	3050		3520	3050		3555	mV
V _{IHCMR}	Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 7)	2.0		5.0	2.0		5.0	2.0		5.0	V
I _{IH}	Input HIGH Current			150			150			150	μA
۱ _{IL}	Input LOW Current	0.5			0.5			0.5			μA

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm.

Input and output parameters vary 1:1 with V_{CC}. V_{EE} can vary +0.5 V to -0.5 V.
 All loading with 50 Ω to V_{CC} - 3.0 V.
 V_{IHCMR} min varies 1:1 with V_{EE}, max varies 1:1 with V_{CC}. The V_{IHCMR} range is referenced to the most positive side of the differential input signal.

			-40°C		25°C				85°C			
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit	
IEE	Power Supply Current	24	30	36	26	34	40	30	36	42	mA	
V _{OH}	Output HIGH Voltage (Note 9)	-1170	-1145	-895	-1120	-964	-845	-1100	-900	-825	mV	
V _{OL}	Output LOW Voltage (Note 9)	-2800	-2516	-2200	-2820	-2514	-2220	-2860	-2478	-2240	mV	
V_{IH}	Input HIGH Voltage (Single-Ended)	-1230		-890	-1130		-810	-1060		-720	mV	
V_{IL}	Input LOW Voltage (Single-Ended)	-1950		-1500	-1950		-1480	-1950		-1445	mV	
VIHCMR	Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 10)	-1.3		0.0	-1	.3	0.0	-1	.3	0.0	V	
I _{IH}	Input HIGH Current			150			150			150	μA	
IIL	Input LOW Current	0.5			0.5			0.5			μA	

Table 6. DC CHARACTERISTICS, NECL V_{CC} = 0 V, V_{EE} = -3.3 V (Note 8)

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm.

8. Input and output parameters vary 1:1 with V_{CC}. V_{EE} can vary +0.3 V to -0.3 V.

9. All loading with 50 Ω to V_{CC} – 3.0 V. 10. V_{IHCMR} min varies 1:1 with V_{EE}, max varies 1:1 with V_{CC}. The V_{IHCMR} range is referenced to the most positive side of the differential input signal.

			−40°C			25°C			85°C			
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit	
IEE	Power Supply Current	27	34	41	30	37	44	33	40	47	mA	
V _{OH}	Output HIGH Voltage (Note 12)	-1170	-1045	-895	-1120	-964	-845	-1100	-900	-825	mV	
V _{OL}	Output LOW Voltage (Note 12)	-3100	-2795	-2500	-3150	-2835	-2550	-3150	-2824	-2550	mV	
V _{IH}	Input HIGH Voltage (Single-Ended)	-1230		-890	-1130		-810	-1060		-720	mV	
V _{IL}	Input LOW Voltage (Single-Ended)	-1950		-1500	-1950		-1480	-1950		-1445	mV	
VIHCMR	Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 13)	-3.2		0.0	-3	3.2	0.0	-3	3.2	0.0	V	
I _{IH}	Input HIGH Current			150			150			150	μA	
١ _{IL}	Input LOW Current	0.5			0.5			0.5			μA	

Table 7. DC CHARACTERISTICS, NECL $V_{CC} = 0V$, $V_{EE} = -5.2$ (Note 11)

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm.

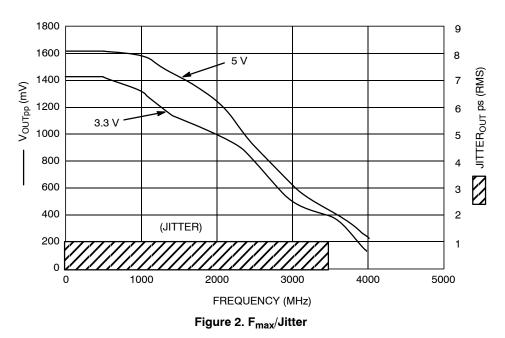
11. Input and output parameters vary 1:1 with V_{CC}. V_{EE} can vary +0.7 V to -0.3 V.

12. All loading with 50 Ω to V_{CC} – 3.0 V. 13. V_{IHCMR} min varies 1:1 with V_{EE}, max varies 1:1 with V_{CC}. The V_{IHCMR} range is referenced to the most positive side of the differential input signal.

			–40°C			25°C		85°C				
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit	
f _{max}	Maximum Toggle (See Figure 2 F _{max} /JITTER)		> 2			> 2			> 2		GHz	
t _{PLH} , t _{PHL}	Propagation Delay to Output Differential	220	280	340	250	310	370	270	330	390	ps	
t _{SKEW}	Within Device SkewQ, \overline{Q} Device to Device Skew (Note 15)		5.0	20 120		5.0	20 120		5.0	20 120	ps	
t _{JITTER}	Cycle-to-Cycle Jitter (See Figure 2 F _{max} /JITTER)		0.5	< 1		0.5	< 1		0.5	< 1	ps	
V _{PP}	Input Voltage Swing (Differential Configuration)	150	800	1200	150	800	1200	150	800	1200	mV	
t _r t _f	Output Rise/Fall TimesQ, \overline{Q} (20% - 80%)	175	250	325	200	275	350	225	295	375	ps	

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm.

14. Measured using a 750 mV source, 50% duty cycle clock source. All loading with 50 Ω to V_{CC}-3.0 V. 15. Skew is measured between outputs under identical transitions.



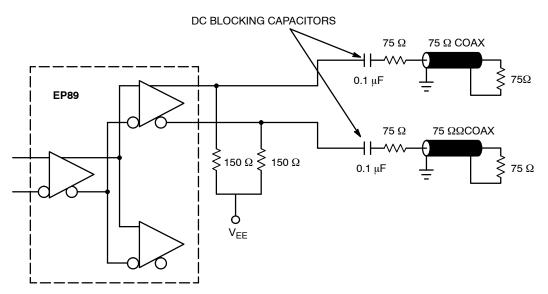
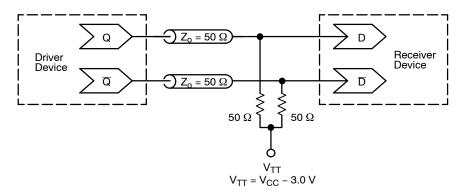


Figure 3. Cable Driver Termination Configuration





Resource Reference of Application Notes

AN1405/D	-	ECL Clock Distribution Techniques	

- AN1406/D Designing with PECL (ECL at +5.0 V)
- AN1503/D ECLinPS™ I/O SPiCE Modeling Kit
- AN1504/D Metastability and the ECLinPS Family
- AN1568/D Interfacing Between LVDS and ECL
- AN1642/D The ECL Translator Guide
- AND8001/D Odd Number Counters Design
- AND8002/D Marking and Date Codes
- AND8020/D Termination of ECL Logic Devices
- AND8066/D Interfacing with ECLinPS
- AND8090/D AC Characteristics of ECL Devices

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*For additional information on our Pb-Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

STYLES ON PAGE 2

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SOIC-8 NB CASE 751-07 ISSUE AK

STYLE 1: PIN 1. EMITTER COLLECTOR 2. COLLECTOR 3. 4. EMITTER 5. EMITTER BASE 6. 7 BASE EMITTER 8. STYLE 5: PIN 1. DRAIN 2. DRAIN З. DRAIN DRAIN 4. GATE 5. 6. GATE SOURCE 7. 8. SOURCE STYLE 9: PIN 1. EMITTER, COMMON COLLECTOR, DIE #1 COLLECTOR, DIE #2 2. З. EMITTER, COMMON 4. 5. EMITTER, COMMON 6 BASE. DIE #2 BASE, DIE #1 7. 8. EMITTER, COMMON STYLE 13: PIN 1. N.C. 2. SOURCE 3 GATE 4. 5. DRAIN 6. DRAIN DRAIN 7. 8. DRAIN STYLE 17: PIN 1. VCC 2. V2OUT V10UT З. TXE 4. 5. RXE 6. VFF 7. GND 8. ACC STYLE 21: PIN 1. CATHODE 1 2. CATHODE 2 3 CATHODE 3 CATHODE 4 4. 5. CATHODE 5 6. COMMON ANODE COMMON ANODE 7. 8. CATHODE 6 STYLE 25: PIN 1. VIN 2 N/C REXT З. 4. GND 5. IOUT 6. IOUT IOUT 7. 8. IOUT STYLE 29: BASE, DIE #1 PIN 1. 2 EMITTER, #1 BASE, #2 З. EMITTER, #2 4. 5 COLLECTOR, #2 COLLECTOR, #2 6.

STYLE 2: PIN 1. COLLECTOR, DIE, #1 2. COLLECTOR, #1 COLLECTOR, #2 3. 4 COLLECTOR, #2 BASE, #2 5. EMITTER, #2 6. 7 BASE #1 EMITTER, #1 8. STYLE 6: PIN 1. SOURCE 2. DRAIN 3. DRAIN SOURCE 4. SOURCE 5. 6. GATE GATE 7. 8. SOURCE STYLE 10: GROUND PIN 1. BIAS 1 OUTPUT 2. З. GROUND 4. 5. GROUND 6 BIAS 2 INPUT 7. 8. GROUND STYLE 14: PIN 1. N-SOURCE 2. N-GATE 3 P-SOURCE P-GATE 4. P-DRAIN 5 6. P-DRAIN N-DRAIN 7. N-DRAIN 8. STYLE 18: PIN 1. ANODE ANODE 2. SOURCE 3. GATE 4. 5. DRAIN 6 DRAIN CATHODE 7. 8. CATHODE STYLE 22: PIN 1. I/O LINE 1 2. COMMON CATHODE/VCC 3 COMMON CATHODE/VCC 4. I/O LINE 3 COMMON ANODE/GND 5. 6. I/O LINE 4 7. I/O LINE 5 8. COMMON ANODE/GND STYLE 26: PIN 1. GND 2 dv/dt З. ENABLE 4. ILIMIT 5. SOURCE SOURCE 6. SOURCE 7. 8. VCC STYLE 30: DRAIN 1 PIN 1. DRAIN 1 2 GATE 2 З. SOURCE 2 4. SOURCE 1/DRAIN 2 SOURCE 1/DRAIN 2 5. 6.

STYLE 3: PIN 1. DRAIN, DIE #1 DRAIN, #1 2. DRAIN, #2 З. DRAIN, #2 4. GATE, #2 5. SOURCE, #2 6. 7 GATE #1 8. SOURCE, #1 STYLE 7: PIN 1. INPUT 2. EXTERNAL BYPASS THIRD STAGE SOURCE GROUND З. 4. 5. DRAIN 6. GATE 3 SECOND STAGE Vd 7. FIRST STAGE Vd 8. STYLE 11: PIN 1. SOURCE 1 GATE 1 SOURCE 2 2. 3. GATE 2 4. 5. DRAIN 2 6. DRAIN 2 DRAIN 1 7. 8. DRAIN 1 STYLE 15: PIN 1. ANODE 1 2. ANODE 1 ANODE 1 3 ANODE 1 4. 5. CATHODE, COMMON CATHODE, COMMON CATHODE, COMMON 6. 7. CATHODE, COMMON 8. STYLE 19: PIN 1. SOURCE 1 GATE 1 SOURCE 2 2. 3. GATE 2 4. 5. DRAIN 2 6. MIRROR 2 7. DRAIN 1 8. **MIRROR 1** STYLE 23: PIN 1. LINE 1 IN COMMON ANODE/GND COMMON ANODE/GND 2. 3 LINE 2 IN 4. LINE 2 OUT 5. COMMON ANODE/GND COMMON ANODE/GND 6. 7. 8. LINE 1 OUT STYLE 27: PIN 1. ILIMIT 2 OVI 0 UVLO З. 4. INPUT+ 5. 6. SOURCE SOURCE SOURCE 7. 8 DRAIN

STYLE 4: PIN 1. 2. ANODE ANODE ANODE З. 4. ANODE ANODE 5. 6. ANODE 7 ANODE COMMON CATHODE 8. STYLE 8: PIN 1. COLLECTOR, DIE #1 2. BASE, #1 BASE #2 З. COLLECTOR, #2 4. COLLECTOR, #2 5. 6. EMITTER, #2 EMITTER, #1 7. 8. COLLECTOR, #1 STYLE 12: PIN 1. SOURCE SOURCE 2. 3. GATE 4. 5. DRAIN 6. DRAIN DRAIN 7. 8. DRAIN STYLE 16 EMITTER, DIE #1 PIN 1. 2. BASE, DIE #1 EMITTER, DIE #2 3 BASE, DIE #2 4. 5. COLLECTOR, DIE #2 6. COLLECTOR, DIE #2 COLLECTOR, DIE #1 7. COLLECTOR, DIE #1 8. STYLE 20: PIN 1. SOURCE (N) GATE (N) SOURCE (P) 2. 3. 4. GATE (P) 5. DRAIN 6. DRAIN DRAIN 7. 8. DRAIN STYLE 24: PIN 1. BASE EMITTER 2. 3 COLLECTOR/ANODE COLLECTOR/ANODE 4. 5. CATHODE

6. CATHODE COLLECTOR/ANODE 7. 8. COLLECTOR/ANODE STYLE 28: PIN 1. SW_TO_GND 2. DASIC OFF DASIC_SW_DET З. 4. GND 5. 6. V MON VBULK 7. VBULK

7. VOULK 8. VIN

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SOURCE 1/DRAIN 2

7.

8. GATE 1

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7.

8

COLLECTOR, #1

COLLECTOR, #1

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-T- SEATING

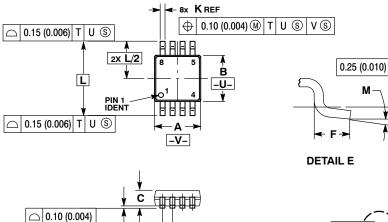
PLANE

D



TSSOP-8 3.00x3.00x0.95 CASE 948R-02 ISSUE A

DATE 07 APR 2000



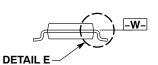
0.25 (0.010)

NOTES:

4.

5.

PER SIDE.



	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
Α	2.90	3.10	0.114	0.122
В	2.90	3.10	0.114	0.122
С	0.80	1.10	0.031	0.043
D	0.05	0.15	0.002	0.006
F	0.40	0.70	0.016	0.028
G	0.65 BSC		0.026 BSC	
K	0.25	0.40	0.010	0.016
L	4.90 BSC		0.193 BSC	
М	0°	6 °	0 °	6 °

NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: MILLIMETER. 3. DIMENSION A DOES NOT INCLUDE MOLD FLASH. PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE. 4. DIMENSION B DOES NOT INCLUDE INTERLED

FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010)

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